

Average Weight: 18.6260g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					1.061350	5.698
	Silicon	7440-21-3	100.00		1.061350	
Solder Bump					0.054318	0.292
	Tin	7440-31-5	63.00		0.034220	
	Lead	7439-92-1	37.00		0.020098	
Underfill					0.044000	0.236
	Silica	60676-86-0	70.00		0.030800	
	Epoxy Resin A	9003-36-5	20.00		0.00800	
	Epoxy Resin B	25068-38-6	3.00		0.001320	
	Hardener	19900-65-3	7.00		0.003080	
Heat Spreader					3.000000	16.107
	Copper	7440-50-8	99.90		2.997000	
	Nickel	7440-02-0	0.10		0.003000	
Heat Spreader Adhesive					0.053000	0.285
	Organopolysiloxane mixture	N/A	100.00		0.053000	
Substrate					13.323982	71.534
	Copper	7440-50-8	47.61	Metal layer	6.250280	
	Nickel	7440-02-0	0.52	Metal layer	0.069285	
	Gold	7440-57-5	0.12	Metal layer	0.015989	
	Glass fiber	N/A	10.50		1.399018	
	Halogen fire retardant	N/A	5.25		0.699509	
	BT (core)	N/A	28.00		3.730715	
	Solder mask	N/A	8.70		1.159186	
Solder Balls					1.089345	5.849
	Tin	7440-31-5	63.00		0.686287	
	Lead	7439-92-1	37.00		0.403058	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
3/23/06	1.0	Initial Xilinx release.
6/09/06	1.1	100% Material Declaration.
9/11/06	1.2	Updated substance weights.
9/28/06	1.3	Updated component descriptions and weights.
7/20/10	1.4	Updated Heat Spreader substance description.

Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.